

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. ..... 09/652,534  
Priority Filing Date ..... August 31, 2000  
Inventor ..... Sujit Sharan et al.  
Assignee ..... Micron Technology, Inc.  
Priority Group Art Unit ..... 2823  
Priority Examiner ..... Trung Q. Dang  
Attorney's Docket No. ..... MI22-2360  
Title: Plasma Enhanced Chemical Vapor Deposition Methods and Semiconductor Processing Methods of Forming Layers and Shallow Trench Isolation Regions

**INFORMATION DISCLOSURE STATEMENT**

References -- See attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a continuation application of co-pending application Serial No. 09/652,534, filed August 31, 2000, upon which the above-identified application relies for a priority date under 35 U.S.C. §120. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. §1.98(d) and MPEP §609(2). Page 1 of 3 lists U.S. patents and a PCT application cited in the parent case, therefore no copies are provided. Two applications are also cited on page 1 of 3, copies of documents related to those applications and available to Applicant are provided. Pages 2 of 3 and 3 of 3 cite cases not previously cited and therefore copies are also provided.

Form PTO-1449  LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI122-2360	SERIAL NO. Filed Herewith			
		APPLICANT Sujit Sharan et al.						
		FILING DATE Filed Herewith		GROUP				
		U.S. PATENT DOCUMENTS						
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
	AA	U.S. Patent Application Serial No. 08/472,329		Abandoned - Specification and drawings.			6/7/95	
	AB	U.S. Patent Application Serial No. 08/813,135		Abandoned - Specification, drawings, No. Of Appeal, Appeal Brief, and Examiner's Answer.			3/7/97	
	AC	6,211,040 B1	04/03/01	Liu et al.				
	AD	6,153,543	11/28/00	Chesire et al.				
	AE	6,030,881	02/29/00	Papasouliotis et al				
	AF	5,981,355	11/09/99	Lee				
	AG	5,968,610	10/19/99	Liu et al.				
	AH	5,920,792	07/06/99	Lin				
	AI	5,915,190	06/22/99	Pirkle				
	AJ	5,913,140	06/15/99	Roche et al.				
	AK							
FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AL	WO 00/03430	01/20/00	PCT				
	AM							
	AN							
	AO							
	AP							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
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	AS							
	AT							
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Citation of these references is respectfully requested.

Respectfully submitted,

Date: 7-16-03

  
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Form PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE <b>LIST OF ART CITED BY APPLICANT</b> (Use several sheets if necessary)					ATTY. DOCKET NO. MI22-2360		SERIAL NO. Filed Herewith	
					APPLICANT Sujit Sharai et al.			
					FILING DATE Filed Herewith		GROUP	
<b>U.S. PATENT DOCUMENTS</b>								
*Examiner Initial		Document Number	Date	Name		Class	Subclass	Filing Date If Appropriate
	AA	US2001/0028922 A1 Serial No. 09/754,440	10/11/01	Published Patent, Petition, Petition, CPA Request, and Preliminary Amendment.				
	AB	5,362,526	11/8/94	Wang et al.				
	AC	5,279,865	01/18/94	Chebi et al.				
	AD	5,271,972	12/21/93	Kwok et al.				
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	AH	5,124,014	06/23/92	Foo et al.				
	AI	5,040,046	08/13/91	Chhabra et al.				
	AJ	4,979,467	12/25/90	Kamaji et al.				
	AK	4,963,239	10/16/90	Shimamura et al.				
<b>FOREIGN PATENT DOCUMENTS</b>								
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							Yes	No
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	AN							
	AO							
	AP							
<b>OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)</b>								
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U.S. PATENT DOCUMENTS									
*Examiner Initial		Document Number	Date	Name		Class	Subclass	Filing Date If Appropriate	
	AA	4,933,058	06/12/90	Bache et al.					
	AB	4,894,352	01/16/90	Lane et al.					
	AC	4,877,641	10/31/89	Dory					
	AD	4,756,810	07/12/88	Lamont, Jr. et al.					
	AE	4,732,761	03/22/88	Machida et al.					
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	AG	4,496,450	01/29/85	Hitotsuyanagi et al.					
	AH	4,147,573	04/03/79	Morimoto					
	AI								
	AJ								
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								Yes	No
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